

3DIC 2024 Program at-a-glance

September 25-27, 2024

Conference Venue:

September 25, 2024 at Hotel Metropolitan Sendai

September 26-27, 2024 at Sendai Kakusai Hotel

as of September 6,

Date	25-Sep-24		26-Sep-24		27-Sep-24		NanoTerasu
Venue	Hotel Metropolitan Sendai		Sendai Kokusai Hotel		Sendai Kokusai Hotel		NanoTerasu
Room	Sendai-East	Sendai-West/South	Heian	Heian & Foyer	Heian	Heian & Foyer	NanoTerasu Visit
9:00			Registration (8:30-)	Preparation for exhibition and poster session (8:30-10:00)	Registration (8:30-)	Preparation	
			Keynote Talk IV (8:50-9:30)		Keynote Talk V (8:50-9:20)		
10:00			Invited Talk IV (9:30-10:00)	Poster & Exhibition (10:00-18:00)	Session 4: Design&Thermal Management (9:20-10:20)	Exhibition (9:00-10:35)	
			Invited Talk V (10:00-10:30)		Coffee Break (10:20-10:35)		
			Coffee Break (10:30-10:45)		Session 5 : Bumpless and Hybrid Bonding Technology (10:35-12:15)		Dismantle by exhibitors (10:35-11:30)
11:00			Session 2: Process Technology for Hybrid Bonding (10:45-11:45)				
12:00			Lunch Time (11:45-13:00)		Award Ceremony & Closing Remarks (12:15-12:30)	Dismantle by organizer (11:30-12:30)	
13:00	Registration (12:00-)						
	Opening Remark (13:00-13:10)		Poster Session (Core time)				
	Keynote Talk I (13:10-13:50)						
14:00	Keynote Talk II (13:50-14:30)		Panel Session (14:30-15:15)				
	Coffee Break (14:30-14:45)						
15:00	Keynote Talk III (14:45-15:25)		Coffee Break (15:15-15:30)				
	Invited Talk I (15:25-15:55)		Invited Talk VI (15:30-16:00)				
16:00	Invited Talk II (15:55-16:25)		Invited Talk VII (16:00-16:30)				
	Invited Talk III (16:25-16:55)		Session 3: Advanced Interposers (16:30-17:30)				
17:00	Session 1 : Quantum Technology (16:45-17:25)						
18:00							
19:00		Banquet (18:00-20:00)					
20:00							
						NanoTerasu Visit (in Japanese) 14:00-15:00	
						NanoTerasu Visit (in English) 15:00-16:00	